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To whom it may concern

Ahrensburg, March 30, 2026

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RoHS Statement

Product: various

Dear Sir or Madam,

Directive 2011/65/EU of 8 June 2011 regulates the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment (EEE).
Prior RoHS Directive 2002/95/EC is repealed as from 3 January 2013.

For the purposes of Directive 2011/65/EU, no more than the maximum concentration value by weight in homogeneous materials as specified in its Annex II, in detail lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), shall be tolerated in EEE placed on the EU market.

Further, **Delegated Directive (EU) 2015/863 of 31 March 2015** amending Annex II to Directive 2011/65/EU has been published by European Commission to add the following phthalates onto the list of restricted substances: Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).

Basler declares that to its knowledge the following products listed in **Annex 1 “RoHS Data”** supplied by us

a) do not use RoHS exemptions listed in 2011/65/EU – Annex III OR

b) use RoHS exemptions under the permission of stated RoHS exemption(s) listed in 2011/65/EU – Annex III OR

c) are compliant and the information on whether RoHS exemptions apply is not available.

Should you require information on RoHS for a product not contained in Annex 1 please contact productmaterialcompliance@baslerweb.com.

Best regards

Birgit Braaker

Birgit Braaker, Head of Legal

Katrin Ziegler, Product and Material Compliance Manager

Part No.	Part Name	RoHS Status	RoHS Exemption
104840	acA750-30gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
104840	acA750-30gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
104840	acA750-30gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105392	acA2500-14gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105392	acA2500-14gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
105392	acA2500-14gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
105393	acA2500-14gc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
105393	acA2500-14gc	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
105393	acA2500-14gc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105573	avA1600-50gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105715	acA2040-25gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
105715	acA2040-25gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
105715	acA2040-25gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105993	raL2048-48gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
105993	raL2048-48gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
105993	raL2048-48gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
105996	raL8192-12gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
105996	raL8192-12gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
105996	raL8192-12gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
106201	acA1300-60gc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106201	acA1300-60gc	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106201	acA1300-60gc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106201	acA1300-60gc	Compliant with Exemption	7.a-I Lead in high melting temperature type solders (i.e., lead-based alloys containing 85% by weight or more lead) for internal interconnections for attaching die, or other components along with a die in semiconductor assembly with steady state or transient/impulse currents of 0.1 A or greater or blocking voltages beyond 10 V, or die edge sizes larger than 0.3 mm x 0.3 mm
106215	acA2500-14um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106215	acA2500-14um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106215	acA2500-14um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106219	acA1600-20um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106219	acA1600-20um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106219	acA1600-20um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106228	acA1920-25um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106228	acA1920-25um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106228	acA1920-25um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106486	acA1280-60gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106486	acA1280-60gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106486	acA1280-60gm	Compliant with Exemption	7.a-I Lead in high melting temperature type solders (i.e., lead-based alloys containing 85% by weight or more lead) for internal interconnections for attaching die, or other components along with a die in semiconductor assembly with steady state or transient/impulse currents of 0.1 A or greater or blocking voltages beyond 10 V, or die edge sizes larger than 0.3 mm x 0.3 mm

Part No.	Part Name	RoHS Status	RoHS Exemption
106486	acA1280-60gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106541	acA2040-90um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106541	acA2040-90um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106681	daA1280-54um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106685	daA1280-54uc (S-Mount)	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106685	daA1280-54uc (S-Mount)	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106685	daA1280-54uc (S-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106691	daA1920-30uc (S-Mount)	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106691	daA1920-30uc (S-Mount)	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106691	daA1920-30uc (S-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106692	daA2500-14um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106693	daA2500-14um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106693	daA2500-14um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106693	daA2500-14um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106695	daA2500-14uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106752	acA1300-200um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106752	acA1300-200um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
106754	acA1300-200uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106754	acA1300-200uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106793	ACA1300-60gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106793	ACA1300-60gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106793	ACA1300-60gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106879	acA1920-155um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106879	acA1920-155um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106907	acA1920-40gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106907	acA1920-40gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106907	acA1920-40gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106909	acA1920-40um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106909	acA1920-40um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106909	acA1920-40um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106944	acA2500-14uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
106944	acA2500-14uc	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
106944	acA2500-14uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106953	puA1280-54um, CS-Mount	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
106954	puA1280-54uc	Compliant	not applicable
106991	puA1600-60uc, CS-Mount	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
107208	acA2440-35um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107208	acA2440-35um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107210	acA2040-55um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107210	acA2040-55um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107211	acA2040-55uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107211	acA2040-55uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107212	acA2440-20gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107212	acA2440-20gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
107212	acA2440-20gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107214	acA2040-35gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107214	acA2040-35gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107214	acA2040-35gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
107215	acA2040-35gc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107215	acA2040-35gc	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
107215	acA2040-35gc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107402	acA3088-57um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107402	acA3088-57um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107404	acA4024-29um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107404	acA4024-29um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
107405	acA4024-29uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107405	acA4024-29uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107496	acA1920-155ucMED	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107496	acA1920-155ucMED	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107647	acA 1440-73gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107647	acA 1440-73gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107647	acA 1440-73gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
107652	acA1440-220um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
107652	acA1440-220um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107961	a2A1920-160umPRO	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
107961	a2A1920-160umPRO	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
107961	a2A1920-160umPRO	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108007	daA2500-60mci-S	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108012	daA4200-30mci (No-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108020	acA720-520um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108020	acA720-520um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108029	a2A2590-60ucBAS	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108029	a2A2590-60ucBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
108105	T-Gate-35 (USB)	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108105	T-Gate-35 (USB)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108165	a2A4504-18um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108165	a2A4504-18um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108165	a2A4504-18um	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108220	daA3840-30mc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108229	daA1920-160um (No-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108234	daA1920-160uc (CS-Mount)	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
108234	daA1920-160uc (CS-Mount)	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108234	daA1920-160uc (CS-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108270	daA3840-45um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108270	daA3840-45um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108272	daA3840-45um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108272	daA3840-45um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108274	daA3840-45uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
108349	atA320-50g-LW-7mm - 17µm IRFPA	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108349	atA320-50g-LW-7mm - 17µm IRFPA	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108349	atA320-50g-LW-7mm - 17µm IRFPA	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108350	atA320-50g-LW-19mm - 17µm IRFPA	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108350	atA320-50g-LW-19mm - 17µm IRFPA	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108350	atA320-50g-LW-19mm - 17µm IRFPA	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108358	a2A4200-12gmBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108358	a2A4200-12gmBAS	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108358	a2A4200-12gmBAS	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108371	a2A2600-64ucBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108371	a2A2600-64ucBAS	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108376	boA5328-100cm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108376	boA5328-100cm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108376	boA5328-100cm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108376	boA5328-100cm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108376	boA5328-100cm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108376	boA5328-100cm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108391	boA6500-36cm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108391	boA6500-36cm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
108391	boA6500-36cm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108410	a2A4096-9gmBAS	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108410	a2A4096-9gmBAS	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108410	a2A4096-9gmBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108413	a2A2840-48ucBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108417	a2A2448-75ucBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108571	a2A640-240gmSWIR	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108571	a2A640-240gmSWIR	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108571	a2A640-240gmSWIR	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108572	a2A1280-80gmSWIR	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108572	a2A1280-80gmSWIR	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108572	a2A1280-80gmSWIR	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108619	daA2448-70um (No-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108711	blaze-102	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108711	blaze-102	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108711	blaze-102	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108729	daA1440-220um	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
108729	daA1440-220um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
108729	daA1440-220um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108730	daA1440-220um (CS-Mount)	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108730	daA1440-220um (CS-Mount)	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
108730	daA1440-220um (CS-Mount)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108751	dart IO board starter kit 2	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108752	dart IO board 2	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108778	acA2040-35gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108778	acA2040-35gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108778	acA2040-35gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
108997	acA720-290gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
108997	acA720-290gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
108997	acA720-290gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109236	a2A2840-48umUV	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109236	a2A2840-48umUV	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109236	a2A2840-48umUV	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
109275	acA4024-29uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109275	acA4024-29uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109332	imaFlex CXP-12 Quad	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
109332	imaFlex CXP-12 Quad	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
109332	imaFlex CXP-12 Quad	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109340	r2L2048-58gm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109340	r2L2048-58gm	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
109340	r2L2048-58gm	Compliant with Exemption	7.a-I Lead in high melting temperature type solders (i.e., lead-based alloys containing 85% by weight or more lead) for internal interconnections for attaching die, or other components along with a die in semiconductor assembly with steady state or transient/impulse currents of 0.1 A or greater or blocking voltages beyond 10 V, or die edge sizes larger than 0.3 mm x 0.3 mm
109340	r2L2048-58gm	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109373	a2A2560-70umSWIR	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109373	a2A2560-70umSWIR	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
109373	a2A2560-70umSWIR	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109482	a2A5060-15umBAS	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109482	a2A5060-15umBAS	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
109482	a2A5060-15umBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109488	a2A3536-31umBAS	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109709	acA5472-17um	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109709	acA5472-17um	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
109710	acA5472-17uc	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
109710	acA5472-17uc	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Part No.	Part Name	RoHS Status	RoHS Exemption
220000315	Power-I/O Cable M8 6p/open, 5 m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2000005670	CS-mount to C-mount adapter	Compliant	information not available
2000024601	Spacer ring 1 mm, C-mount	Compliant	information not available
2000026249	Spacer ring 0.5mm, C-mount	Compliant	information not available
2000027038	Cable GigE Cat 6,S/STP,1xSL hori,DrC,5m	Compliant	not applicable
2000027039	Cable GigE Cat 6,S/STP,1xSL hori,DrC,20m	Compliant	not applicable
2000028338	Cable GigE Cat 6,S/STP,1xSL vert,DrC,20m	Compliant	not applicable
2000028339	Cable GigE Cat 6,S/STP,1xSL vert,DrC,10m	Compliant	not applicable
2000028340	Cable GigE Cat 6,S/STP,1xSL vert,DrC,5m	Compliant	not applicable
2000028341	Cable GigE Cat 6,S/STP,1xSL hori,DrC,10m	Compliant	not applicable
2000029411	Power-I/O Cable HRS 6p/open, tw, 10 m	Compliant	not applicable
2000029551	Cable GigE Cat 6,S/STP,1xSL hori,DrC,25m	Compliant	not applicable
2000030285	Cable GigE Cat 6, SFTP, 2xRJ-45, 10 m	Compliant	information not available
2000030288	Cable GigE Cat 6a, S/FTP, 2xRJ-45, 50 m	Compliant	not applicable
2000031081	PoCL Kabel Camera Link SDR/SDR Full 10m	Compliant	not applicable
2000031082	PoCL Kabel Camera Link SDR/MDR Full 3m	Compliant	not applicable
2000031084	PoCL Kabel Camera Link SDR/MDR Full 10m	Compliant	not applicable
2000032041	C-mount for boost R, racer	Compliant	not applicable
2000032201	F-mount for boost, racer, Basler beat	Compliant	not applicable
2000033239	Cable USB 3.0, Micro B screwlock/A, 3 m	Compliant	not applicable
2000033241	Cable USB 3.0, Micro B screwlock/A, 5 m	Compliant	not applicable
2000034086	Opto-I/O Cable 6p/open, 10	Compliant	not applicable
2000034087	GP-I/O Cable 6p/open, 10 m	Compliant	not applicable
2000034676	Cable USB 3.0,Micro B sl 90°A14/A, 0.15m	Compliant	not applicable
2000034832	Basler Lens C125-0818-5M f8mm	Compliant	not applicable
2000034833	Basler Lens C125-1218-5M f12mm	Compliant	not applicable
2000034834	Basler Lens C125-1620-5M f16mm	Compliant	not applicable
2000034891	Cable USB 3.0, Micro B screwlock/A, 8 m	Compliant	not applicable
2000034904	Lens Ricoh FL-CC1214A-2M F1.4 f12mm 2/3"	Compliant	not applicable
2000035012	Mount boost racer B beat	Compliant	not applicable
2000035070	Lens Edmund Optics CFFL F2.0 f50mm 2/3"	Compliant	not applicable
2000035315	Cable USB 3.0, Micro B / A, 3 m	Compliant	not applicable
2000035612	Lens Evetar M13B02820W F2.0 f2.8mm 13	Compliant	
2000035665	dart IO board mounting kit	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2000035665	dart IO board mounting kit	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
2000035699	Cable GigE Cat5eS/STP,1xSL hz,RBC,Cst,5m	Compliant	not applicable
2000035891	Cable USB 3.0, Micro B 90° A3 / A, 1 m	Compliant	not applicable
2000035892	Cable USB 3.0, Micro B 90° A3 / A, 3 m	Compliant	not applicable
2000035929	Cable USB 3.0, Micro B 90° A3 / A, 5 m	Compliant	not applicable
2000035953	CS-mount to S-mount adapter	Compliant	information not available
2000035994	Cable USB 3.0, MicroB 90°A1 sl / A, 3 m	Compliant	not applicable
2000035995	Cable USB 3.0, MicroB 90°A1 sl / A, 5 m	Compliant	not applicable
2000036231	Cable USB 3.0,Ext. 10m A female / A male	Compliant	not applicable
2000036232	Cable USB 3.0,Ext. 20m A female / A male	Compliant	not applicable
2000036234	USB 3.0 Hub, 4 Ports side by side	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2000036234	USB 3.0 Hub, 4 Ports side by side	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
2000036234	USB 3.0 Hub, 4 Ports side by side	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2000036234	USB 3.0 Hub, 4 Ports side by side	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2000036234	USB 3.0 Hub, 4 Ports side by side	Compliant with Exemption	7.c-II Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher

Part No.	Part Name	RoHS Status	RoHS Exemption
2000036369	Cable USB 3.0, MicroB 90°A1 sl / A, 1 m	Compliant	not applicable
2200000038	Cable USB 3.0, Micro B 90° R1sl / A 3m N	Compliant	not applicable
2200000089	Cable USB 3.0, Mirco B sl / A, 3m, HQ	Compliant	not applicable
2200000129	Cable GigE Cat5eS/STP,1xSL hz,Cst,5m,bl	Compliant	not applicable
2200000130	Cable USB 3.0, Mcr B/A Flat Cable, 0,15m	Compliant	not applicable
2200000137	Cable USB 3.0, McrB 90°A3/F, 0.93m	Compliant	not applicable
2200000138	Cable USB 3.0, McrB 90° A14/F, 0.82m	Compliant	not applicable
2200000139	Cable USB 3.0, McrB 90°A12/F, 0.68m	Compliant	not applicable
2200000164	dart mounting cover	Compliant	not applicable
2200000190	Cable USB 3.0, Micro B sl/A, CC, 0.5 m	Compliant	not applicable
2200000199	Cable GigE Cat 6,S/STP,1xSL hori,5m, CNX	Compliant	not applicable
2200000204	Cable USB 3.0, Micro B screwlock/A, 1 m	Compliant	not applicable
2200000249	Cable USB 3.0,Ext. 15m A female / A male	Compliant	not applicable
2200000269	Basler CXP-12 Interface Card 1C	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
2200000269	Basler CXP-12 Interface Card 1C	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000269	Basler CXP-12 Interface Card 1C	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000284	Cable GigE M12,m,8p/RJ45,10m	Compliant	not applicable
2200000296	Power-I/O Cable M8 6p/open, 10 m	Compliant	information not available
2200000297	Cable USB 3.0 Hybrid, Micro B sl/A, 10 m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000315	Power-I/O Cable M8 6p/open, 5 m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000317	Heat sink for Basler boost R cameras	Compliant	not applicable
2200000320	Cable CXP, Micro-BNC x2 (HD-BNC), 3 m	Compliant	not applicable
2200000321	Cable CXP, Micro-BNC x2 (HD-BNC), 5 m	Compliant	not applicable
2200000322	Cable CXP, Micro-BNC x2 (HD-BNC), 10 m	Compliant	not applicable
2200000324	Cable BCON, 200mm	Compliant	information not available
2200000327	Basler SLP Cable HRS 6p/TBL-L, 3m	Compliant	not applicable
2200000330	Basler SLP Cable TBL-L/open, 1.5m	Compliant	not applicable
2200000363	microEnable 5 marathon VF2	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000363	microEnable 5 marathon VF2	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000363	microEnable 5 marathon VF2	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000444	Adapterkabel USB2.0, Mini B, Micro B	Compliant	not applicable
2200000464	Cable USB 3.0, McrB 90° A32/F, 0.5m	Compliant	not applicable
2200000465	Cable USB 3.0, McrB 90° A32/F, 1.2m	Compliant	not applicable
2200000482	imaWorx CXP-12 Quad	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000482	imaWorx CXP-12 Quad	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000482	imaWorx CXP-12 Quad	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000516	Screw Lock for Thunderbolt optical cable	Compliant	not applicable
2200000518	T-Gate2-35 (USB)	Compliant	information not available
2200000568	Lens Basler C23-0824-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
2200000569	Lens Basler C23-1224-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000570	Lens Basler C23-1620-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000571	Lens Basler C23-2518-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000572	Lens Basler C23-3520-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000573	Lens Basler C23-5028-5M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000574	Lens Basler C11-0824-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000575	Lens Basler C11-1220-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000576	Lens Basler C11-1620-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000577	Lens Basler C11-2520-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000578	Lens Basler C11-3520-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000579	Lens Basler C11-5020-12M	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000589	Evetar E3360D IR-Cut F2.0 f4mm 11.8”	Compliant	not applicable
2200000591	T-Gate2_50	Compliant	information not available
2200000593	Thunderbolt Device IF (lüfterlos)	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000593	Thunderbolt Device IF (lüfterlos)	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000620	Cable USB 3.0, Micro B sl/A, S, 1m	Compliant	not applicable
2200000621	Cable USB 3.0, Micro B sl/A, S, 3m	Compliant	not applicable
2200000622	Cable GigE, Cat6a, RJ45 1xSL hor, S, 5m	Compliant	not applicable
2200000623	Cable GigE, Cat6a, RJ45 1xSL hor, S, 10m	Compliant	not applicable
2200000624	Cable GigE, Cat6a, RJ45 1xSL hor, S, 20m	Compliant	not applicable
2200000625	Power-I/O Cable HRS 6p/open, S, 5m	Compliant	not applicable
2200000626	Power-I/O Cable HRS 6p/open, S, 10m	Compliant	not applicable
2200000694	Lens Fujinon CF8ZA-1S F1.8 f8mm 1.2"	Compliant	not applicable
2200000695	Lens Fujinon CF12ZA-1S F1.8 f12mm 1.2"	Compliant	not applicable
2200000696	Lens Fujinon CF16ZA-1S F1.8 f16mm 1.2"	Compliant	not applicable
2200000697	Lens Fujinon CF25ZA-1S F1.8 f25mm 4/3"	Compliant	not applicable
2200000698	Lens Fujinon CF35ZA-1S F1.8 f35mm 4/3"	Compliant	not applicable
2200000699	Lens Fujinon CF50ZA-1S F2.4 f50mm 4/3"	Compliant	not applicable
2200000701	Basler CXP-12 Interface Card 2C	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000701	Basler CXP-12 Interface Card 2C	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000701	Basler CXP-12 Interface Card 2C	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000702	Basler CXP-12 Interface Card 4C	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000702	Basler CXP-12 Interface Card 4C	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000702	Basler CXP-12 Interface Card 4C	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
2200000707	Basler IP-Housing ace USB Body	Compliant	not applicable
2200000710	Basler IP-Housing Lens Tube 50mm	Compliant	not applicable
2200000712	Basler IP-Housing Lens Tube 70mm	Compliant	not applicable
2200000716	Basler GigE Interface Card, 4 Port	Compliant	not applicable
2200000718	Basler GigE Interface Card, 2 Port PoE	Compliant	not applicable
2200000719	Basler GigE Interface Card, 4 Port PoE	Compliant	not applicable
2200000734	Basler Light Ring-70OD-White	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000750	Basler Light Dome-200OD-White	Compliant	information not available
2200000898	BL cable M8, 2m, axial	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
2200000898	BL cable M8, 2m, axial	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000899	BSL Cable M8 5m axial	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000959	dart mounting cover	Compliant	not applicable
2200000969	M25 cable gland single hole	Compliant	not applicable
2200000970	M25 cable gland double hole	Compliant	not applicable
2200000972	rc_visard 160c	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000972	rc_visard 160c	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000972	rc_visard 160c	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000972	rc_visard 160c	Compliant with Exemption	15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
2200000973	rc_visard 160m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000973	rc_visard 160m	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000973	rc_visard 160m	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000973	rc_visard 160m	Compliant with Exemption	15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
2200000974	rc_visard 65c	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000974	rc_visard 65c	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000974	rc_visard 65c	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000974	rc_visard 65c	Compliant with Exemption	15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
2200000975	rc_visard 65m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.

Part No.	Part Name	RoHS Status	RoHS Exemption
2200000975	rc_visard 65m	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000975	rc_visard 65m	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000975	rc_visard 65m	Compliant with Exemption	15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
2200000976	rc_visard 160m-6	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200000976	rc_visard 160m-6	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200000976	rc_visard 160m-6	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200000976	rc_visard 160m-6	Compliant with Exemption	15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
2200000998	Fischer Elektronik ace2 heat sink	Compliant	not applicable
2200001000	Thunderbolt Device IF3 (fanless)	Compliant	information not available
2200001079	Cable USB 3.0, McrB 90°A3/F, 0.93m, gr m	Compliant	not applicable
2200001088	Cable USB 3.1 TypeA MicroB ScrewLock 10m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001089	Cable USB 3.1 TypeA MicroB ScrewLock 15m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001146	BSL Barlight Mount 4x90° rectangle	Compliant	information not available
2200001164	Kabel USBMicB3.0 90DA34, USBA3.0 0.6m	Compliant	
2200001166	Thunderbolt Device IF3	Compliant	information not available
2200001166	Thunderbolt Device IF 3	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200001166	Thunderbolt Device IF 3	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200001168	USB Dongle for License Activation for Commercial Use	Compliant	not applicable
2200001177	imaFlex CXP-12 Penta	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001177	imaFlex CXP-12 Penta	Compliant with Exemption	6.a Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight
2200001177	imaFlex CXP-12 Penta	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200001177	imaFlex CXP-12 Penta	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200001179	Neousys 5GigE Card, 4 Port PoE	Compliant	not applicable
2200001188	Light Controller 2C-1.25A-50W-24V	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001188	Light Controller 2C-1.25A-50W-24V	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).

Part No.	Part Name	RoHS Status	RoHS Exemption
2200001188	Light Controller 2C-1.25A-50W-24V	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200001188	Light Controller 2C-1.25A-50W-24V	Compliant with Exemption	7.c-II Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
2200001189	Light Controller 4C-1.25A-84W-24V	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001189	Light Controller 4C-1.25A-84W-24V	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200001189	Light Controller 4C-1.25A-84W-24V	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200001189	Light Controller 4C-1.25A-84W-24V	Compliant with Exemption	7.c-II Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
2200001190	BLC DC trig connector 5-Pin	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001191	BLC Din Rail	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001192	BLC-BSL connect cable M8, 2m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001193	BLC-BSL connect cable M8, 5m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001194	BLC-BSL connect cable M8, 8m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001195	AC Power Cord USA NEMA 5-15, 1.8m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001196	AC Power Cord EU IEC60884-1 CEE7/7, 1.8m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001197	AC Power Cord UK/SIN BS 1363-1, 1.8m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001198	AC Power Cord China GB 2008, 1.8m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001199	AC Power Cord Taiwan CNS-690, 1.5m	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001211	boA5120-150ccGMAX0505	Compliant	not applicable
2200001230	Cable USB 3.0, McrB 90°A3/F, 5m r	Compliant	not applicable
2200001231	Cable USB 3.0, McrB 90°A3/F, 5m g	Compliant	not applicable
2200001232	Cable USB 3.0, McrB 90° A14/F, 5m b	Compliant	not applicable
2200001233	Cable USB 3.0, McrB 90° A12/F, 5m w	Compliant	not applicable
2200001249	Cable USB 3.0, McrB sl A3, 8m w/o Vbus	Compliant	not applicable
2200001264	BLC DC trig connector 7-Pin	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200001408	Lens, Computar M0828-MPW3	Compliant	information not available
2200001660	Basler Standard Lens C12-0824-25MP	Compliant	not applicable
2200001661	Basler Standard Lens C12-1224-25MP	Compliant	not applicable
2200001662	Basler Standard Lens C12-1624-25MP	Compliant	not applicable
2200001663	Basler Standard Lens C12-2524-25MP	Compliant	not applicable
2200001664	Basler Standard Lens C12-3524-25MP	Compliant	not applicable
2200001665	Basler Standard Lens C12-5024-25M	Compliant	not applicable
2200001666	10M-HR6FOPHF-PIO	Compliant	information not available
2200001667	15M-HR6FOPHF-PIO	Compliant	information not available
2200001668	16M-HR6FOPHF-PIO	Compliant	information not available
2200001669	17M-HR6FOPHF-PIO	Compliant	information not available
2200001670	20M-HR6FOPHF-PIO	Compliant	information not available
2200001671	10M-LRHF-GIGE	Compliant	information not available
2200001672	13M-LRHF-GIGE	Compliant	information not available
2200001673	14M-LRHF-GIGE	Compliant	information not available
2200001674	15M-LRHF-GIGE	Compliant	information not available

Part No.	Part Name	RoHS Status	RoHS Exemption
2200001675	17M-LRHF-GIGE	Compliant	information not available
2200001676	18M-LRHF-GIGE	Compliant	information not available
2200001701	Cable Y USB3.0 to F6p/M6p, AF, 3M	Compliant	not applicable
2200001807	Flat Flex Cable dart M 15cm	Compliant	not applicable
2200001808	Flat Flex Cable dart M 30cm	Compliant	not applicable
2200002034	Cable Y USB3.0 to M8M6p/HRSM6p, AF, 3M	Compliant	not applicable
2200002102	dart M IO Cable, IDCopen, 500mm	Compliant	not applicable
2200002204	Basler USB Interface Card,1HC,5G,2Port	Compliant	not applicable
2200002205	Basler USB Interface Card,1HC,10G,2Port	Compliant	not applicable
2200002206	Basler USB Interface Card,1HC,5G,4Port	Compliant	not applicable
2200002207	Basler USB Interface Card,4HC,5G,4Port	Compliant	not applicable
2200002208	Basler USB Interface Card,4HC,5G,8Port	Compliant	not applicable
2200002274	Power-I/O Cable RS-422 M8 6p/open, 10 m	Compliant	not applicable
2200002318	8M-LRHF-GIGE	Compliant	information not available
2200002319	8M-HR6FOPHF-PIO	Compliant	information not available
2200002339	Basler 5GigE Interface Card, 4 Port PoE+	Compliant	not applicable
2200002340	Basler 5GigE Interface Card, 4 Port	Compliant	not applicable
2200002351	imaFlex CXP-12 Quad	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200002351	imaFlex CXP-12 Quad	Compliant with Exemption	7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
2200002351	imaFlex CXP-12 Quad	Compliant with Exemption	7.c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors ,e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
2200002372	Basler Lens C23-3528-16M f35mm	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200002384	Compressed Air Cooler ace 2 / racer 2 S	Compliant	not applicable
2200002427	Basler 2.5GigE Interface Card, 1 Port	Compliant	not applicable
2200002428	Basler 2.5GigE Interface Card, 4-CH PoE+	Compliant	not applicable
2200002429	Basler 10GigE Interface Card, 2-CH	Compliant	not applicable
2200002430	Basler 10GigE Interface Card, 2-CH PoE+	Compliant	not applicable
2200002432	Basler 10GigE Interface Card, 4-CH	Compliant	not applicable
2200002433	Basler 10GigE Interface Card, 4-CH PoE+	Compliant	not applicable
2200002825	Light Bar-10x100-White-Diffuse	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200002833	Stereo mini STM-501u	Compliant	not applicable
2200002834	Stereo mini STM-502u	Compliant	not applicable
2200002835	Stereo mini STM-951u	Compliant	not applicable
2200002836	Stereo mini STM-951g	Compliant	not applicable
2200002837	Stereo mini STM-951mg	Compliant	not applicable
2200002838	Stereo mini STM-952u	Compliant	not applicable
2200002839	Stereo mini STM-955g	Compliant	not applicable
2200002862	BL Cable M8 4p female / M8 4p male, 0.25	Compliant with Exemption	6.c Lead as an alloying element as copper alloy containing up to 4 % lead by weight.
2200002892	Evetar E3360D IR-Cut F2.0 f4mm 1/1.8"TR	Compliant	not applicable